

EPE component testing



Learn why epe is the missing component in your supply chain

cmos x 400

EPE Components Product Quality Testing.

- **ISO 9001-2015B CERTIFIED**
- **AS9120B; AS6081 COMPLIANT**
- **Member of the globally recognized ERAI**
(Electronics Resellers Association International)
- **EPE maintains a Documented Mitigation Program (DCM) & Counterfeit Prevention Program (CPP) within its Quality Management System (QMS)**
- **EPE has an In-House product quality testing laboratory.**



Innovative and reactive supply chain solutions.

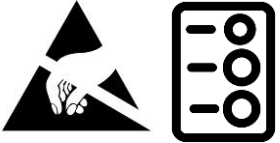


- Founded in 2002
- Privately held
- Global Operations
- Trusted Partner
- Global distribution network

Quality Testing Objectives.



- Determine that the correct component is being supplied.



- Determine that the component has been handled and packaged correctly (ESD and MSD control)



- Determine that the component passes Visual Inspection and does not show any evidence of damage, corrosion, oxidation or physical imperfections.



- Determine that the component is new.

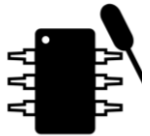


- Determine that the component is not counterfeit.

Quality Testing Capabilities.



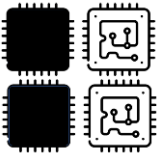
- EVI – External Visual Inspection.



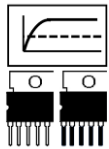
- Remarking and Resurfacing Testing.



- XRAY Inspection and Comparison to Golden Sample



- Decapsulation Inspection and Comparison to Golden Sample



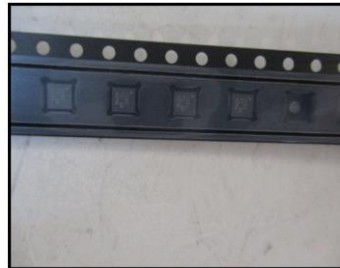
- Solderability Performance Confirmation.

Quality Testing Procedure - EVI.

- Verify part does not have existing counterfeit reports on ERAI & GIDEP
- Take images of the outside of the packaging.
- Take images of the paperwork, labels, ESD packaging, humidity cards.
- Look for and take images of condition of the part packaging (reels, tape, etc.)
- Take images under the microscope (100x-600x)
Take top, bottom, and side (45-degree side angle) images, note all parts markings and compare to OCM's data sheet
- Measure the dimensions of the part (vs. data sheet) and weigh the part- if applicable
- Inspect leads and terminals for damage (bent, used, oxidation, solder remnants)
- Record Findings.

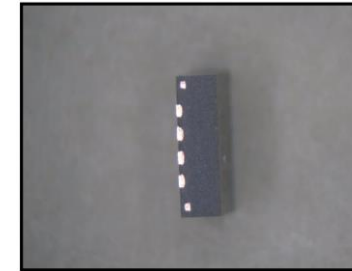
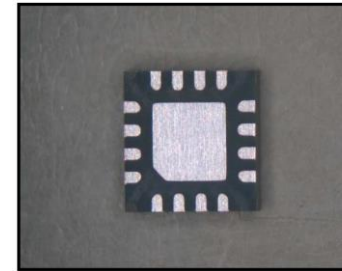
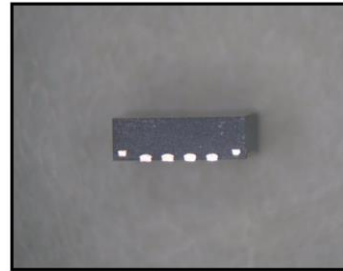
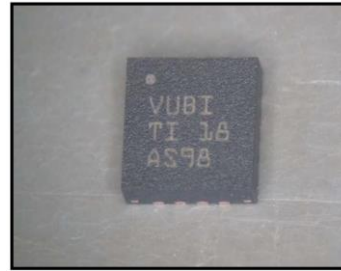
EVI - Detail

- EVI – External Visual Inspection. PACKING



EVI - Detail

- EVI – External Visual Inspection. - DEVICE

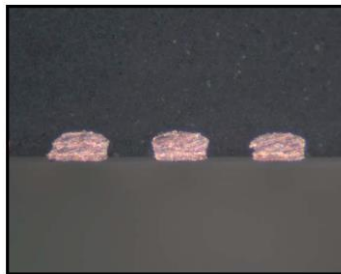
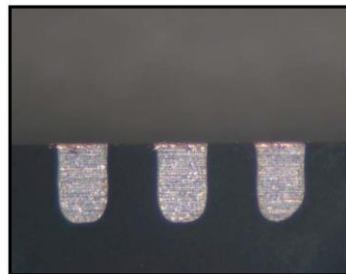


- Dimensional Check



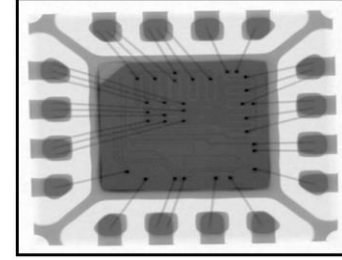
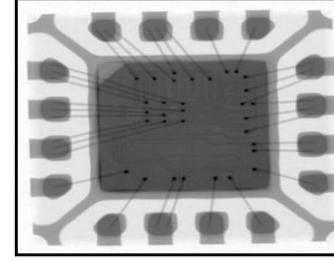
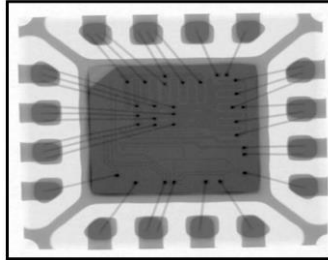
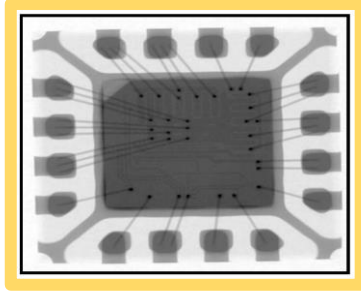
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- Terminal / Lead Inspection

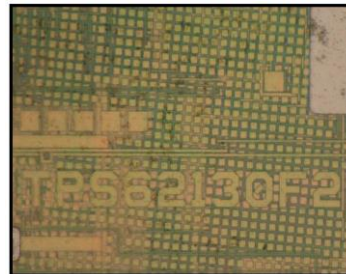
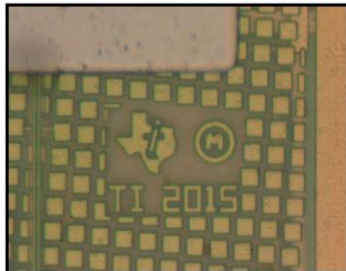
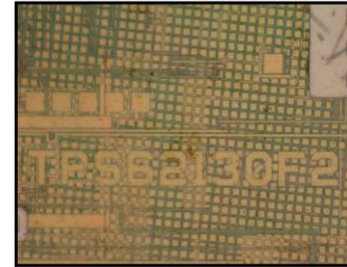
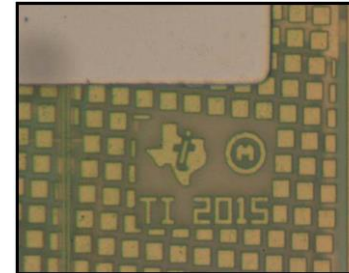
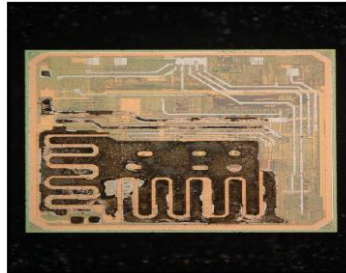
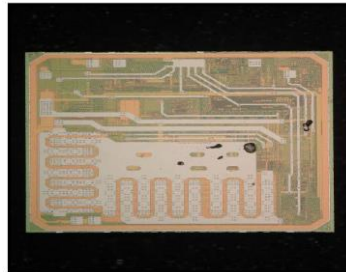


X-Ray and Decapsulation Inspection

- XRAY Inspection.

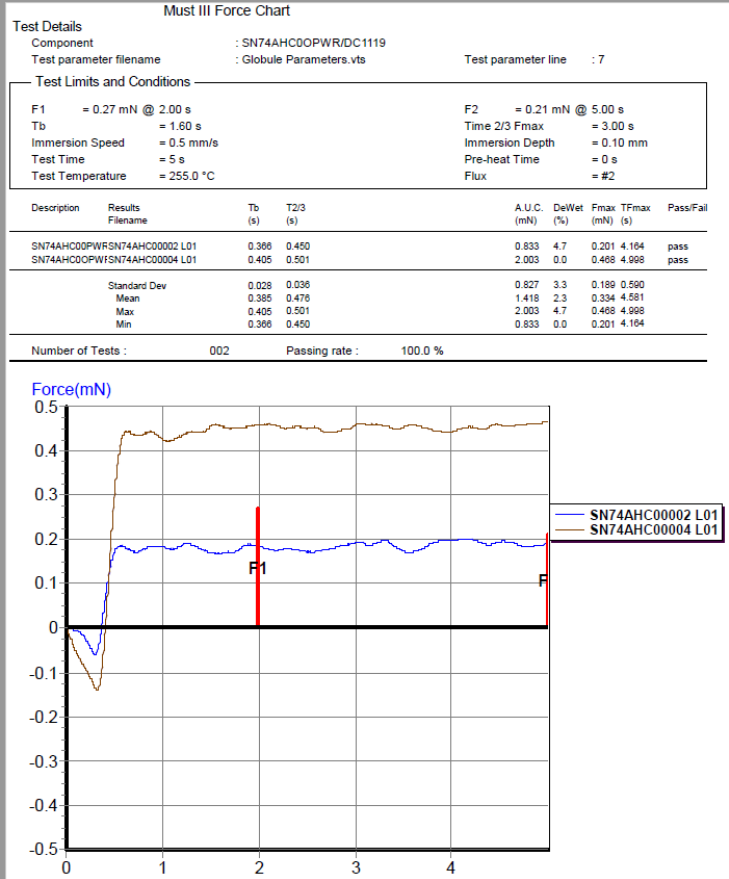
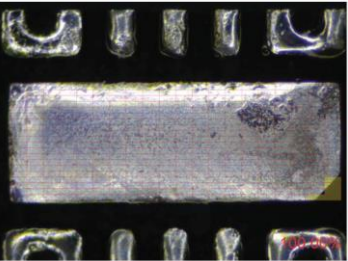
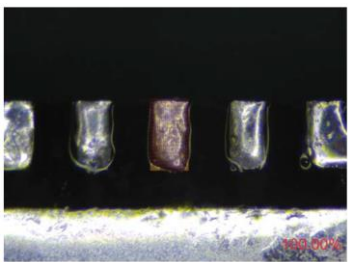
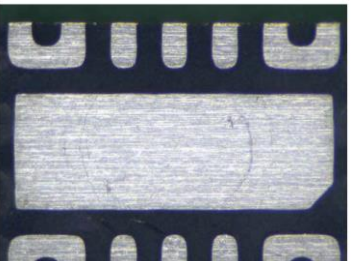
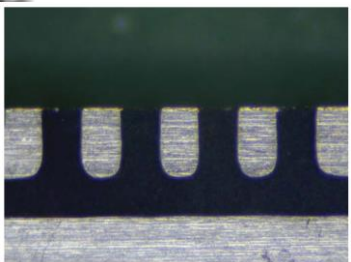
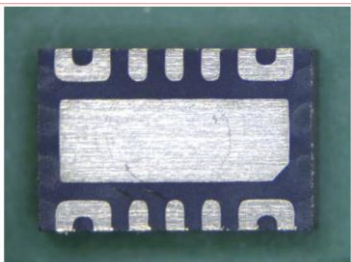
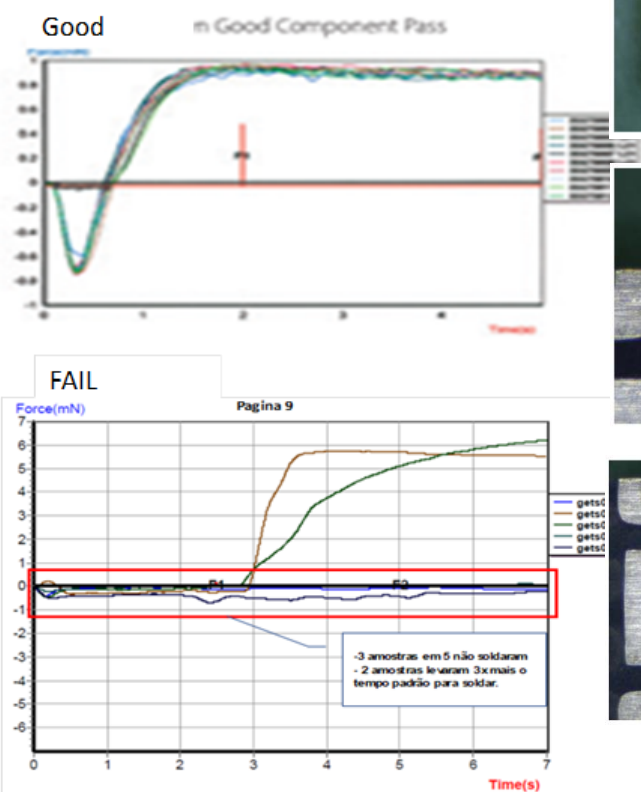


- DECAPSULATION Inspection



SOLDERABILITY – Wetting Balance

○ Solderability



EQUIPMENT

- KEYENCE Advanced Microscope



- Decapsulation



- SEAMARK X6600 XRAY

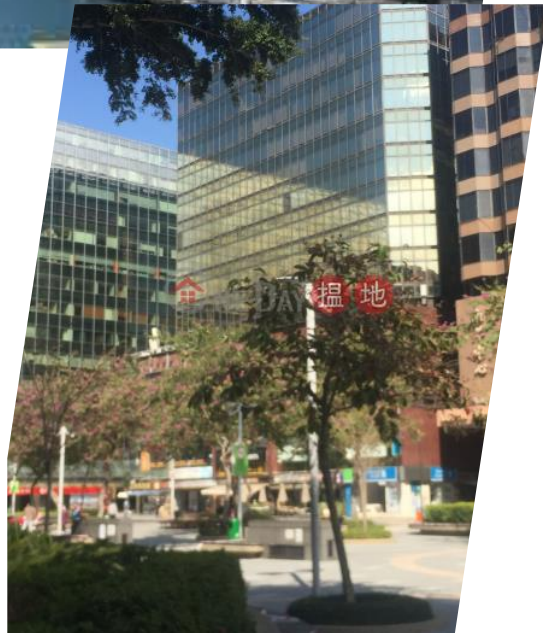


- GEN3 MUST III Wetting Balance Solderability Tester



Reporting

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